

# EUROPEAN PATENT OFFICE

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TITLE : CREAM SOLDER

ABSTRACT : PURPOSE: To improve the infiltratability of cream solder by incorporating specific ratios of a polystyrene resin, dimethyl silicone resin and liquid paraffin into this cream solder.

CONSTITUTION: This flux contains at least  $\geq 2$  kinds of the polystyrene resin, the dimethyl silicone resin and the liquid paraffin. The contents of the polystyrene resin, the dimethyl silicone resin and the liquid paraffin are respectively specified to 0 to 3wt.% and the total of the respective contents is specified to 0.5 to 3wt.%. The polystyrene resin, dimethyl silicone resin and liquid paraffin added into the flux act as external lubricants and improve the slip between the cream solder and the apertures of a screen mask. The infiltratability at the time of printing is improved and the remaining at the screen mask is lessened. The dimethyl silicone resin and liquid paraffin improve the thixotropic property of the cream solder as well and decreases shear droops at the time of printing.

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